

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C1	1	2.2uF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
C2	1	22uF	CAP, CERM, xxxF, 6.3V, X7R, xx%, [PackageReference]	1206	Used in BOM report	Used in BOM report
C3	1	33uF	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Used in PnP output	EKXG401ELL330ML20S	Used in BOM report
C4, C5	2	0.1uF	CAP, Film, 0.1uF, 630V, +/-20%, TH	B32922 10.5mm	B32922C3104M	EPCOS Inc
C6	1	1500pF	CAP, CERM, 1500pF, 630V, X7R, xx%, [PackageReference]	1206	Used in BOM report	Used in BOM report
C7	1	4.7uF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	1206		Used in BOM report
C8	1	220uF	CAP, AL, 220uF, 35V, +/-20%, 0.16 ohm, SMD	SMT Radial F	EEE-FK1V221P	Panasonic
C9	1	22uF	CAP, AL, 22uF, 25V, +/-20%, 1 ohm, SMD	SMT Radial D	EEE-FC1E220P	Panasonic
C10	1	1uF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
C11	1	82pF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
C12	1	0.01uF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
C13	1	DNP	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
C14	1	100pF	CAP, CERM, xxxF, 50V, X7R xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
C15	1	120pF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
C16	1	47nF	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
C17, C18	2	3300pF	Capacitor, Ceramic Disk, 220V	0.394 X 0.315 inch Max.	ECKANA332ME	Panasonic
D1	1	DF04S	Diode, Switching-Bridge, 400V, 1A, DF-S	DF-S	DF04S	Vishay-Semiconductor
D2	1	US1J	Diode, [Type], xxxV, x.xxV, [PackageReference]	Used in PnP output	Used in BOM report	Used in BOM report
D3	1		Diode, Schottky, xxV, xxV, [PackageReference]	Used in PnP output	MURS120	Used in BOM report
D4	1		Diode, P-N, 200V, 200A, SOT-23	SOT-23	BAS20	Micro Commercial Component
D5	1	15V	DIODE ZENER 15V 500MW SOD-123	SOD123	MMSZ5245BT	On Semi
F1	1	1A	Fuse, Slow Blow, 1A	0.335 inch	37211000001	Wickmann
L1	1	10uH	Inductor, Shielded Drum Core, Ferrite, 10uH, 0.75A, 0.35 ohm, SMD	LPS4012	LPS4012-103MLB	Coilcraft
L2	1	10mH	Coupled inductor, 10mH	17.5x22x13 mm	744822110	Würth Elektronik eiSos
Q1	1	BSS126	MOSFET, Nch, 600V, 7 mA, 700 Ohm	SOT23	BSS126	Infineon

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
Q2	1	FDD5N60NZ	MOSFET, N-CH, xxV, xxxA, DPAK	Used in PnP output	FDD5N60NZ	Used in BOM report
R1	1	100k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R2, R13	2	49.9	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R3, R7	2	10k	RES, xxx ohm, x%, xW, [PackageReference]	1206	Used in BOM report	Used in BOM report
R4	1	150	RES, xxx ohm, x%, xW, [PackageReference]	1206	Used in BOM report	Used in BOM report
R5	1	47k	RES, xxx ohm, x%, xW, [PackageReference]	2010	Used in BOM report	Used in BOM report
R6	1	1.21M	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R8	1	383k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R9	1	DNP	RES, xxx ohm, x%, xW, [PackageReference]	Used in PnP output	1206	Used in BOM report
R10	1	2M	RES, xxx ohm, x%, xW, [PackageReference]	0805	Used in BOM report	Used in BOM report
R11	1	30.1	RES, xxx ohm, x%, xW, [PackageReference]	0805	Used in BOM report	Used in BOM report
R12	1	95.3k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R14	1	0	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R15	1	2.1k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R16	1	28.7k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R17	1	DNP	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R18	1	90.9k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R19	1	0.43	RES, xxx ohm, x%, xW, [PackageReference]	1206	Used in BOM report	Used in BOM report
R20	1	10k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R21	1	15k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R22	1	4.87k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
RV1	1	TBD	Varistor, Disk, 350V, 1W, TA @ 85C°	D Size	SIOV-S20K275	Epcos
T1	1	800uH	Transformer, 800uH, TH	Transformer, 25x16x22.2 mm	750314149r01	Würth Elektronik eiSos
TP1, TP4, TP8	3	Red	Test Point, TH, Miniature, Red	Keystone5000	5000	Keystone
TP2	1	Red	Test Point, TH, Multipurpose, Red	Keystone5010	5010	Keystone
TP3, TP9	2	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
TP5	1	Black	Test Point, TH, Multipurpose, Black	Keystone5011	5011	Keystone
TP6, TP7	2	Double	Terminal, Turret, TH, Double	Keystone1503-2	1503-2	Keystone
U1	1	TPS62175DQC	IC,	TDFN-10	TPS62175DQC	TI
U2	1	LM5023MM	IC, AC-DC Quasi-Resonant Current Mode PWM Controller	MSOP	LM5023MM	National Semi
U3	1	FOD817A	IC, Optocoupler, xx-V, yy% CTR	SMT-4PDIP	FOD817xx	Fairchild
U4	1		Low-Voltage (1.24V) Adjustable Precision Shunt Regulators, 3-pin SOT-23, Pb-Free	MF03A	LMV431AIMFX/NOPB	National Semiconductor

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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